

IN THE SPECIFICATION

Please amend the Abstract of the Disclosure on page 39 of the application as follows:

An integrated circuit includes a portion having at least one active circuit area. The integrated circuit also includes a redistribution metal layer fabricated at least partially during fabrication of the portion of the integrated circuit. A method for fabricating an integrated circuit includes fabricating a portion of the integrated circuit, where the portion includes at least one active circuit area. The method also includes fabricating a redistribution metal layer at least partially during fabrication of the portion of the integrated circuit.

~~A system and method is disclosed for providing a redistribution metal layer in an integrated circuit. The redistribution metal layer is formed from the last metal layer in the integrated circuit during manufacture of the integrated circuit before final passivation is applied. The last metal layer provides sites for solder bump pads used in flip chip interconnection. The redistribution metal layer can be (1) a flat layer deposited over the next to last metal layer through an opening in a dielectric layer, or (2) deposited over an array of vias connected to the next to last metal layer. Space between the solder bump pads is deposited with narrower traces for connecting active circuit areas below. A final passivation layer is deposited to ensure product reliability.~~